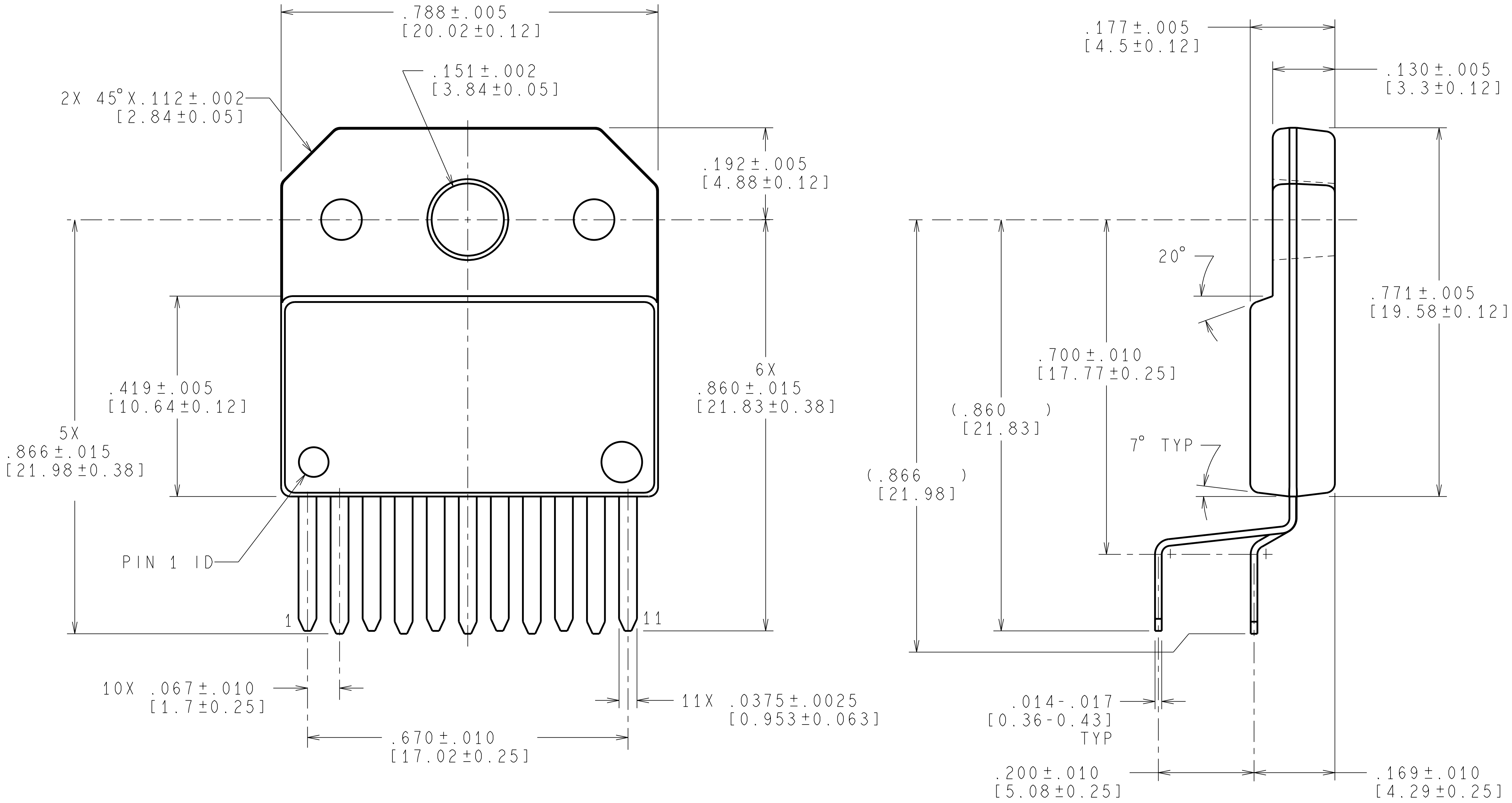
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	09435	11/18/1992	MS/FL
B	CHANGE ALL DRAFT ANGLES TO BE 7°	09488	01/26/1993	MS/FL
C	.783-.793 WAS .778-.798; .035-.040 WAS .034-.040; .014-.017 WAS .013-.017; REVISE NOTE 2.	09435	11/18/1992	MS/FL
D	UPDATE TITLE; REDRAW ON PROE2001.	738	04/07/2003	MS/RW



CONTROLLING DIMENSION IS INCH
VALUES IN [ ] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).

2. REFERENCE JEDEC REGISTRATION MO-168, VARIATION AA.

APPROVALS	DATE
DRAWN MARTA SUCHY	04/07/2003
DFTG. CHK. THANH LEQUANG	04/07/2003
ENGR. CHK. RANDALL WALBERG	04/07/2003

PROJECTION
INCH
[MM]

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

TO-220,MOLDED,
.788x.771x.177in BODY,11 LD,
.067in PITCH,STAG,ISO

SCALE	SIZE	DRAWING NUMBER	REV
NTS	B	(SC)MKT-TF11B	D

FORMERLY: N/A
SHEET 1 of 1